

**Special Issue of the *International Journal of Intelligent
Automation and Soft Computing (AutoSoft)***

Official Publication of World Automation Congress (WAC) (wacong.org)



***Special Issue on Embedded System and Software
for Intelligent Pervasive Computing***

Overview:

Pervasive computers, networks and information are paving a road towards a smart world in which computational intelligence is distributed throughout the physical environment to provide trustworthy and relevant services to people. This intelligent pervasive computing (IPC) will change the computing landscape because it will enable new breeds of applications and systems to be developed. By embedding digital intelligence in everyday objects, our workplaces, our homes and even ourselves, many tasks and processes could be simplified, made more efficient, safer and more enjoyable. Intelligent pervasive computing composes these many "intelligent objects" to create the environments that underpin the smart world.

The scope of this special issue is on all views of embedded system and software for IPC. The call is addressed to scientists and engineers, who design, develop, and implement embedded system and software for IPC. We encourage scientists and engineers from both academic and industrial environments to submit their works in order to enhance the knowledge, expertise, and experience of the whole community in embedded system and software for IPC.

The topics include, but are not limited to, the following:

- Embedded Hardware Support for IPC
- Embedded Software for IPC
- Embedded System Architecture for IPC
- Real-time OS for IPC
- Smart and Personal devices for IPC
- Mobile and Wearable computers and devices for IPC
- Power-Aware computing for IPC
- Middleware for IPC

- Specification, Validation and Verification of Embedded System and Software
- Security issues of Embedded System and Software
- New Technologies and Devices for IPC
- New Applications and Services of IPC
- Industrial Practices for IPC

Because the International Journal of Intelligent Automation and Soft Computing (AutoSoft) is the official publication of WAC, submitted manuscripts should not be considered for publication by other journals or any other conferences (except the WAC congress, see wacong.org), which have proceedings.

Manuscripts, which have appeared previously in proceedings of conferences, could be submitted to this special issue if they are substantially revised or improved from their earlier versions, due to copyright issues. Submissions must be sent via email to: Dr. Jong Hyuk Park (parkjonghyuk@gmail.com) and Prof. Laurence T. Yang (lyang@gmail.com).

Please note that AutoSoft Journal has a nominal page charge of US \$ 600 per 12 final pages and \$ 100 per page afterwards. This contribution to expenses of the journal will bring with it a full 1-year subscription, 25 reprints. AutoSoft is the world's first technical journal on soft computing (computational intelligence) and its abstracts are indexed internationally including ISI services and Elsevier Publishers in Amsterdam.

This special issue additionally selects high quality papers (best papers) from the IPC-07 (<http://www.sersc.org/IPC2007>), Korea, December 2007.

Important Dates:

Manuscript Submission Deadline: September 1, 2007

1st Notification of acceptance: October 31, 2007

Submission due date of revised Manuscript: November 30, 2007

2nd Notification of acceptance: December 31, 2007

Submission of final revised Manuscript: January 31, 2008

Publication date: 3rd or 4th Quarter, 2008 (Tentative)

Manuscript submissions must conform to the layout and format guidelines in the AutoSoft Instructions for Contributors: <http://wacong.org/autosoft.html>.

AutoSoft Journal Manuscripts are abstracted in many services in the US, Europe and the Far East.

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